## Our Series 58XX - the fully automatic bonder on a desktop

Can do everything a fully automatic wire bonder can do, but fits on a table: this is our Series 58XX. With the latest developments the Model 5830 for example, a Wedge bonder for thin wire, achieves 2 wires per second and is thus optimally suited for volume production.





"Lot size 1, set-up time 0" is the motto of the entire machine family. This is made possible, above all, by the extremely user-friendly software, which customers are unanimously enthusiastic about. Even extremely complicated loop shapes with several reverse points can be drawn on the screen very easily. This allows even intricate and very tight component geometries to be perfectly bonded. The integrated motion control system then ensures that the path curves are run smoothly at high speed.

Another unique feature of the software is PadCapture. This special image recognition function allows the user to mark a desired bond point anywhere on a bond pad with the mouse. The image recognition unit then surveys the bond pad automatically and, without further programming, determines its center of gravity and shifts the bond point precisely there. Chips with many bond pads are programmed in no time, which could have been a work of patience in the past.



And another strength: if you own one of the models from the 58XX family, you can easily convert to any other model, because only the bond head has to be exchanged. The software is virtually identical, so that the operator or engineer can work with the bonder in the shortest possible time.

From Ball-bonding to Heavy-Wire-bonding in only 3 minutes - that is a world record!

Interessted? Visit us at the SMT Hybrid Packaging in Nürnberg and experience the latest technology live! **Get your free day ticket here!** 



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